

SNOSAQ3B-NOVEMBER 2010-REVISED MAY 2013

LMH6715QML Dual Wideband Video Op Amp

Check for Samples: LMH6715QML

FEATURES

- Available with Radiation Ensured 300 krad(Si) $T_A = 25^{\circ}C$, $R_L = 100\Omega$, Typical Values Unless Specified.
- Very Low Diff. Gain, Phase: 0.02%, 0.02°
- Wide Bandwidth: 480MHz (A_V = +1V/V); 400MHz (A_V = +2V/V)
- 0.1dB Gain Flatness to 100MHz
- Low Power: 5.8mA/Channel
- –70dB Channel-to-Channel Crosstalk (10MHz)
- Fast Slew Rate: 1300V/µs
- Unity Gain Stable
- Improved Replacement for CLC412

APPLICATIONS

- HDTV, NTSC & PAL Video Systems
- Video Switching and Distribution
- IQ Amplifiers
- Wideband Active Filters
- Cable Drivers
- DC Coupled Single-to-Differential Conversions

DESCRIPTION

The LMH6715 combines Texas Instrument's VIP10[™] high speed complementary bipolar process with Texas Instrument's current feedback topology to produce a very high speed dual op amp. The LMH6715 provides 400MHz small signal bandwidth at a gain of +2V/V and 1300V/µs slew rate while consuming only 5.8mA per amplifier from ±5V supplies.

The LMH6715 offers exceptional video performance with its 0.02% and 0.02° differential gain and phase errors for NTSC and PAL video signals while driving up to four back terminated 75 Ω loads. The LMH6715 also offers a flat gain response of 0.1dB to 100MHz and very low channel-to-channel crosstalk of -70dB at 10MHz. Additionally, each amplifier can deliver 70mA of output current. This level of performance makes the LMH6715 an ideal dual op amp for high density, broadcast quality video systems.

The LMH6715's two very well matched amplifiers support a number of applications such as differential line drivers and receivers. In addition, the LMH6715 is well suited for Sallen Key active filters in applications such as anti-aliasing filters for high speed A/D converters. Its low power requirement, low noise and distortion allow the LMH6715 to serve portable RF applications such as IQ channels.

Connection Diagram

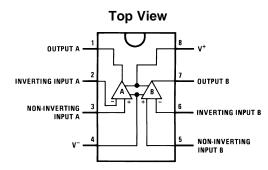


Figure 1. 8 Lead CDIP Package See Package Number NAB0008A



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. VIP10 is a trademark of Texas Instruments.

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Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V _{CC})	±6.75V		
Common Mode Input Voltage (V	V ⁺ - V ⁻		
Differential Input Voltage			V+ - V-
Power Dissipation (P _D) ⁽²⁾			1.0W
Lead Temperature (Soldering, 10) seconds)		+300°C
Junction Temperature (T _J)	+175°C		
Storage Temperature Range			-65°C ≤ T _A ≤ +150 °C
		CDIP (Still Air)	140°C/W
	θ_{JA}	CDIP (500LF/Min Air Flow)	80°C/W
Thermal Resistance		CDIP	32°C/W
Weight CDIP	1130mg		
ESD Tolerance ⁽³⁾	2000V		

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limit s. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), (2) θ_{JA} (package junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{Dmax} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. Human body model, 1.5k Ω in series with 100 pF.

(3)

Recommended Operating Ratings

Supply Voltage (V _{CC})	$\pm 5V_{DC}$ to $\pm 6V_{DC}$
Ambient Operating Temperature Range (T _A)	-55°C ≤ T _A ≤ +125°C

Quality Conformance Inspection

MIL-STD-883, Method 5005 - Group A

Subgroup	Description	Temp (°C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55



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LMH6715 Electrical Characteristics DC Parameter Static and DC Tests

The following conditions apply, unless otherwise specified.

 $R_L = 100\Omega, V_{CC} = \pm 5V_{DC}, A_V = +2, R_F = 634\Omega, -55^{\circ}C \le T_A \le +125^{\circ}C$

Symbol	Parameter	Conditions	Notes	Min	Мах	Unit	Sub- groups
I _{BN}	Input Bias Current, Noninverting		See ⁽¹⁾	-12	12	μA	1
				-12	+12	μA	2
				-20	+20	μA	3
I _{BI}	Input Bias Current, Inverting		See ⁽¹⁾	-21	+21	μA	1
				-25	+25	μA	2
				-35	+35	μA	3
V _{IO}	Input offset voltage		See ⁽¹⁾	-6	6	mV	1
				-12	12	mV	2
				-10	10	mV	3
I _{CC}	Supply Current	R _L =∞	See ⁽¹⁾		14.0	mA	1
					14.0	mA	2
					16.0	mA	3
PSRR	Power Supply Rejection Ration	$+V_{S} = +4.5V \text{ to } +5.0V,$ $-V_{S} = -4.5V \text{ to } -5.0V$		46		dB	1
		$-V_{\rm S} = -4.5$ V to -5.0 V		44		dB	2, 3

(1) Pre and post irradiation limits are identical to those listed under electrical characteristics. These parts may be dose rate sensitive in a space environment and demonstrate enhanced low dose rate effect. Radiation end point limits for the noted parameters are ensured only for the conditions as specified in MIL-STD-883, Method 1019.

LMH6715 Electrical Characteristics AC Parameter Frequeuncy Domain Response

The following conditions apply, unless otherwise specified. $R_L = 100\Omega$, $V_{CC} = \pm 5V_{DC}$, $A_V = +2$, $R_F = 634\Omega$, $-55^{\circ}C \le T_A \le +125^{\circ}C$

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub- groups
SS _{BW}	Small signal bandwith	−3dB BW, V_{OUT} < 0.5 V_{PP}	See ⁽¹⁾	175		MHz	4
GFP	Gain flatness peaking high	0.1MHz to 30 MHz, V _{OUT} ≤ 0.5V _{PP}	See ⁽¹⁾		0.1	dB	4
GFR	Gain flatness rolloff	0.1MHz to 30 MHz, V _{OUT} ≤ 0.5V _{PP}	See ⁽¹⁾		0.3	dB	4

(1) Group A testing only.

LMH6715 Electrical Characteristics AC Parameter Distortion and Noise Response

The following conditions apply, unless otherwise specified.

 $R_{L} = 100\Omega, V_{CC} = \pm 5V_{DC}, A_{V} = +2, R_{F} = 634\Omega, -55^{\circ}C \le T_{A} \le +125^{\circ}C$

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub- groups
HD ₂	Second harmonic distortion	2V _{PP} at 20 MHz	See ⁽¹⁾		-42	dBc	4
HD ₃	Third harmonic distortion	2V _{PP} at 20 MHz	See ⁽¹⁾		-46	dBc	4

(1) Group A testing only.

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LMH6715 Electrical Characteristics DC Parameter Drift Values

The following conditions apply, unless otherwise specified.

Deltas not required on B Level product. Deltas required for S Level product at Group B5 only, or as specified on the Internal Processing Instructions (IPI).

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub- groups
I _{BN}	Input Bias Current, Noninverting		See ⁽¹⁾	-1.2	+1.2	μA	1
I _{BI}	Input Bias Current, Inverting		See ⁽¹⁾	-2.0	+2.0	μA	1
V _{IO}	Input Offset Voltage		See ⁽¹⁾	-1.0	+1.0	mV	1
I _{CC}	Supply Current	R _L = ∞	See ⁽¹⁾	-1.0	+1.0	mA	1

(1) If not tested, shall be specified to the limits specified.

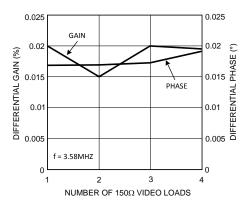


Figure 2. Differential Gain and Phase with Multiple Video Loads

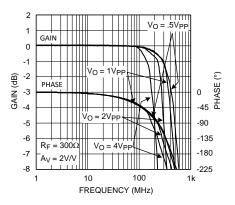


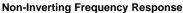
Figure 3. Frequency Response vs. V_{OUT}

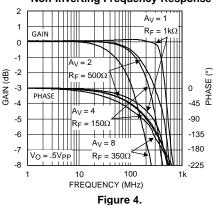


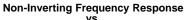


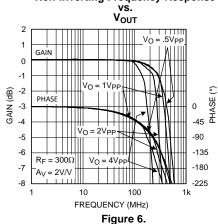
Typical Performance Characteristics

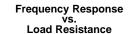
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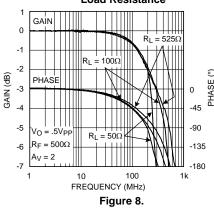


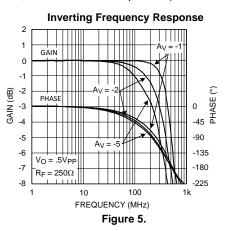




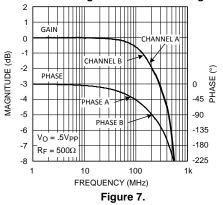




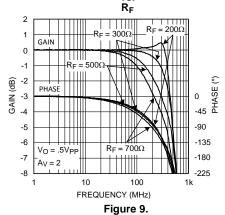




Small Signal Channel Matching



Non-Inverting Frequency Response vs.



Typical Performance Characteristics (continued) $(T_A = 25^{\circ}C, V_{CC} = \pm 5V, A_V = \pm 2V/V, R_F = 500\Omega, R_L = 100\Omega$, unless otherwise specified). Small Signal Pulse Response Large Signal Pulse Response 0.5 3 $R_F = 300\Omega$ V_O = .5V_{PP} 2 0.25 1 Vout (V) Vout (V) 0 0 -1 -0.25 $R_F = 300\Omega$ -2 $V_O = 4V_{PP}$ -0.5 -3 10 15 20 25 30 35 40 45 50 5 0 5 10 15 20 25 30 35 40 45 50 0 TIME (ns) TIME (ns) Figure 10. Figure 11. Settling Time vs. Accuracy Input-Referred Crosstalk -20 1 R_F = 300Ω -30 Vo = .5Vpp SETTLING ACCURACY (%) -40 CROSSTALK (dBc) -50 0.1 -60 -70 -80 -90 0.01 1 10 100 1k 0 5 10 15 20 25 30 35 40 45 50 FREQUENCY (MHz) TIME (ns) Figure 12. Figure 13. DC Errors vs. Temperature -3dB Bandwidth vs. V_{OUT} 500 1.2 -1 $R_F = 300\Omega$ 450 -2 1 I_{BN} -3 BANDWIDTH (MHz) 400 0.8 350 l_{BI} and l_{BN} (μA) 0.6 -4 Vos (mV) Vos 300 0.4 -5 250 0.2 -6 IBI 3dB 200 0 -7 150 -0.2 -8 100 -0.4 -9 0 0.5 1 1.5 2 2.5 3 3.5 4 -40 0 40 80 120 160 V_{OUT} (V_{PP}) TEMPERATURE ()

Figure 14.

Figure 15.

6



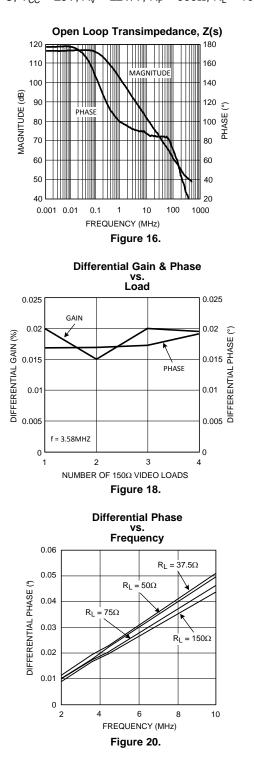
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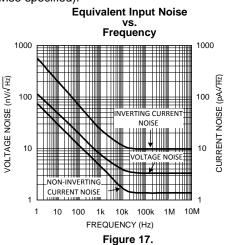


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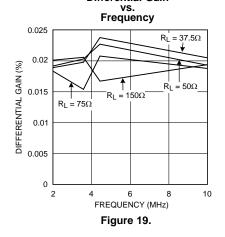
Typical Performance Characteristics (continued)

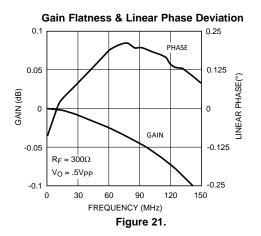
 $(T_A = 25^{\circ}C, V_{CC} = \pm 5V, A_V = \pm 2V/V, R_F = 500\Omega, R_L = 100\Omega$, unless otherwise specified).





Differential Gain





EXAS NSTRUMENTS

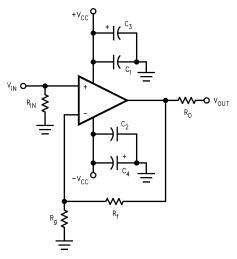
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 $(T_A = 25^{\circ}C, V_{CC} = \pm 5V, A_V = \pm 2V/V, R_F = 500\Omega, R_L = 100\Omega$, unless otherwise specified). **3rd Harmonic Distortion** 2nd Harmonic Distortion vs. Output Voltage vs. Output Voltage -40 -30 $R_F = 500\Omega$ -40 -50 7 -50 2nd HARMONIC (dBc) -60 20MHz 3rd HARMONIC (dBc) 10MH -60 7 -70 20MH2 -70 -80 -80 5MHz 10MH -90 -90 $R_F = 500\Omega$ 5MHz -100 -100 1 2 5 6 0 3 4 0 1 2 3 4 5 6 7 7 VOUT (VPP) VOUT (VPP) Figure 22. Figure 23. **Closed Loop Output Resistance PSRR & CMRR** 70 100 $R_F = 500\Omega^2$ 60 OUTPUT RESISTANCE (Ω) PSRF 10 CMRR and PSRR (dB) 50 40 1 CMR 30 20 0.1 10 RL 5000 0.01 0 0.01 0.1 100 0.01 0.1 10 100 10 1k 1 1k 1 FREQUENCY (MHz) FREQUENCY (MHz) Figure 24. Figure 25. Suggested R_S vs. C_L 100 90 80 SUGGESTED R_S (Ω) 70 60 50 40 30 20 10 0 ∟ 10 100 1000

CAPACITIVE LOAD (pF) Figure 26.

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APPLICATION SECTION





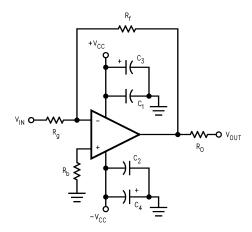


Figure 28. Inverting Configuration with Power Supply Bypassing

Application Introduction

Offered in an 8-pin package for reduced space and cost, the wideband LMH6715 dual current-feedback op amp provides closely matched DC and AC electrical performance characteristics making the part an ideal choice for wideband signal processing. Applications such as broadcast quality video systems, IQ amplifiers, filter blocks, high speed peak detectors, integrators and transimpedance amplifiers will all find superior performance in the LMH6715 dual op amp.

FEEDBACK RESISTOR SELECTION

One of the key benefits of a current feedback operational amplifier is the ability to maintain optimum frequency response independent of gain by using appropriate values for the feedback resistor (R_F). The Electrical Characteristics and Typical Performance plots specify an R_F of 500 Ω , a gain of +2V/V and ±5V power supplies (unless otherwise specified). Generally, lowering R_F from it's recommended value will peak the frequency response and extend the bandwidth while increasing the value of R_F will cause the frequency response to roll off faster. Reducing the value of R_F too far below it's recommended value will cause overshoot, ringing and, eventually, oscillation.

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TEXAS INSTRUMENTS

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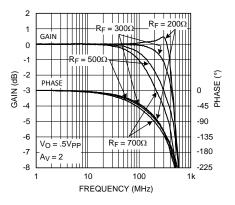


Figure 29. Frequency Response vs. R_F

The plot labeled "Frequency Response vs. R_F " shows the LMH6715's frequency response as R_F is varied ($R_L = 100\Omega$, $A_V = +2$). This plot shows that an R_F of 200 Ω results in peaking and marginal stability. An R_F of 300 Ω gives near maximal bandwidth and gain flatness with good stability, but with very light loads ($R_L > 300\Omega$) the device may show some peaking. An R_F of 500 Ω gives excellent stability with good bandwidth and is the recommended value for most applications. Since all applications are slightly different it is worth some experimentation to find the optimal R_F for a given circuit. For more information see Application Note OA-13 which describes the relationship between R_F and closed-loop frequency response for current feedback operational amplifiers.

When configuring the LMH6715 for gains other than +2V/V, it is usually necessary to adjust the value of the feedback resistor. The two plots labeled " R_F vs. Non-inverting Gain" and " R_F vs. Inverting Gain" provide recommended feedback resistor values for a number of gain selections.

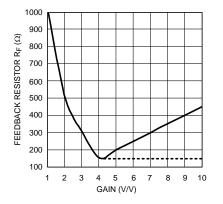


Figure 30. R_F vs. Non-Inverting Gain

Both plots show the value of R_F approaching a minimum value (dashed line) at high gains. Reducing the feedback resistor below this value will result in instability and possibly oscillation. The recommended value of R_F is depicted by the solid line, which begins to increase at higher gains. The reason that a higher R_F is required at higher gains is the need to keep R_G from decreasing too far below the output impedance of the input buffer. For the LMH6715 the output resistance of the input buffer is approximately 160 Ω and 50 Ω is a practical lower limit for R_G . Due to the limitations on R_G the LMH6715 begins to operate in a gain bandwidth limited fashion for gains of ±5V/V or greater.



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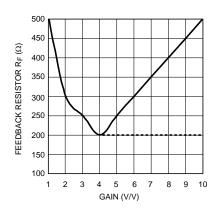


Figure 31. R_F vs. Inverting Gain

When using the LMH6715 as a replacement for the CLC412, identical bandwidth can be obtained by using an appropriate value of R_F . The chart "Frequency Response vs. R_F " shows that an R_F of approximately 700 Ω will provide bandwidth very close to that of the CLC412. At other gains a similar increase in R_F can be used to match the new and old parts.

CIRCUIT LAYOUT

With all high frequency devices, board layouts with stray capacitances have a strong influence over AC performance. The LMH6715 is no exception and its input and output pins are particularly sensitive to the coupling of parasitic capacitances (to AC ground) arising from traces or pads placed too closely (<0.1") to power or ground planes. In some cases, due to the frequency response peaking caused by these parasitics, a small adjustment of the feedback resistor value will serve to compensate the frequency response. Also, it is very important to keep the parasitic capacitance across the feedback resistor to an absolute minimum.

The performance plots in the data sheet can be reproduced using the evaluation boards available from Texas Instruments. The LMH730036 board uses all SMT parts for the evaluation of the LMH6715. The board can serve as an example layout for the final production printed circuit board.

Care must also be taken with the LMH6715's layout in order to achieve the best circuit performance, particularly channel-to-channel isolation. The decoupling capacitors (both tantalum and ceramic) must be chosen with good high frequency characteristics to decouple the power supplies and the physical placement of the LMH6715's external components is critical. Grouping each amplifier's external components with their own ground connection and separating them from the external components of the opposing channel with the maximum possible distance is recommended. The input (R_{IN}) and gain setting resistors (R_F) are the most critical. It is also recommended that the ceramic decoupling capacitor (0.1µF chip or radial-leaded with low ESR) should be placed as closely to the power pins as possible.

POWER DISSIPATION

Follow these steps to determine the Maximum power dissipation for the LMH6715:

1. Calculate the quiescent (no-load) power: P_{AMP} = I_{CC} (V_{CC} - V_{EE})

2. Calculate the RMS power at the output stage: $P_O = (V_{CC} - V_{LOAD})(I_{LOAD})$, where V_{LOAD} and I_{LOAD} are the voltage and current across the external load.

3. Calculate the total RMS power: $Pt = P_{AMP} + P_{O}$

The maximum power that the LMH6715, package can dissipate at a given temperature can be derived with the following equation:

 $Pmax = (150^{\circ} - Tamb) / \theta_{JA}$

where

- Tamb = Ambient temperature (°C)
- θ_{JA} = Thermal resistance, from junction to ambient, for a given package (°C/W)

For the CDIP package θ_{JA} is 140°C/W.

(1)



MATCHING PERFORMANCE

With proper board layout, the AC performance match between the two LMH6715's amplifiers can be tightly controlled as shown in Typical Performance plot labeled "Small-Signal Channel Matching".

The measurements were performed with SMT components using a feedback resistor of 300Ω at a gain of +2V/V.

The LMH6715's amplifiers, built on the same die, provide the advantage of having tightly matched DC characteristics.

SLEW RATE AND SETTLING TIME

One of the advantages of current-feedback topology is an inherently high slew rate which produces a wider full power bandwidth. The LMH6715 has a typical slew rate of $1300V/\mu s$. The required slew rate for a design can be calculated by the following equation:

$$SR = 2\pi f V_{pk}$$

(2)

Careful attention to parasitic capacitances is critical to achieving the best settling time performance. The LMH6715 has a typical short term settling time to 0.05% of 12ns for a 2V step. Also, the amplifier is virtually free of any long term thermal tail effects at low gains.

When measuring settling time, a solid ground plane should be used in order to reduce ground inductance which can cause common-ground-impedance coupling. Power supply and ground trace parasitic capacitances and the load capacitance will also affect settling time.

Placing a series resistor (R_s) at the output pin is recommended for optimal settling time performance when driving a capacitive load. The Typical Performance plot labeled " R_s and Settling Time vs. Capacitive Load" provides a means for selecting a value of R_s for a given capacitive load.

DC AND NOISE PERFORMANCE

A current-feedback amplifier's input stage does not have equal nor correlated bias currents, therefore they cannot be canceled and each contributes to the total DC offset voltage at the output by the following equation:

$$V_{OFFSET} = \pm \left[I_{BN} \times R_{S} \left[1 + \frac{R_{f}}{R_{g}} \right] + V_{IO} \left[1 + \frac{R_{f}}{R_{g}} \right] + I_{BI} \times R_{f} \right]$$
(3)

The input resistance is the resistance looking from the non-inverting input back toward the source. For inverting DC-offset calculations, the source resistance seen by the input resistor R_g must be included in the output offset calculation as a part of the non-inverting gain equation. Application Note OA-7 gives several circuits for DC offset correction. The noise currents for the inverting and non-inverting inputs are graphed in the Typical Performance plot labeled "Equivalent Input Noise". A more complete discussion of amplifier input-referred noise and external resistor noise contribution can be found in Application Note OA-12.

DIFFERENTIAL GAIN & PHASE

The LMH6715 can drive multiple video loads with very low differential gain and phase errors. The Typical Performance plots labeled "Differential Gain vs. Frequency" and "Differential Phase vs. Frequency" show performance for loads from 1 to 4. The Electrical Characteristics table also specifies performance for one 150 Ω load at 4.43MHz. For NTSC video, the performance specifications also apply. Application Note OA-24 "Measuring and Improving Differential Gain & Differential Phase for Video", describes in detail the techniques used to measure differential gain and phase.

I/O VOLTAGE & OUTPUT CURRENT

The usable common-mode input voltage range (CMIR) of the LMH6715 specified in the Electrical Characteristics table of the data sheet shows a range of ± 2.2 volts. Exceeding this range will cause the input stage to saturate and clip the output signal.

The output voltage range is determined by the load resistor and the choice of power supplies. With ± 5 volts the class A/B output driver will typically drive ± 3.9 V into a load resistance of 100Ω . Increasing the supply voltages will change the common-mode input and output voltage swings while at the same time increase the internal junction temperature.



Applications Circuits

SINGLE-TO-DIFFERENTIAL LINE DRIVER

The LMH6715's well matched AC channel-response allows a single-ended input to be transformed to highly matched push-pull driver. From a 1V single-ended input the circuit of Figure 32 produces 1V differential signal between the two outputs. For larger signals the input voltage divider ($R_1 = 2R_2$) is necessary to limit the input voltage on channel 2.

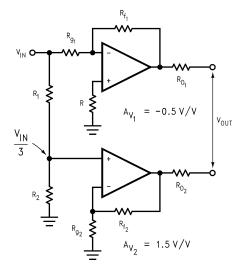
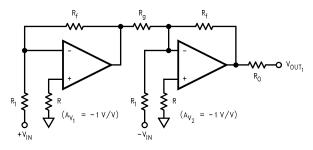


Figure 32. Single-to-Differential Line Driver

DIFFERENTIAL LINE RECEIVER

Figure 33 and Figure 34 show two different implementations of an instrumentation amplifier which convert differential signals to single-ended. Figure 34 allows CMRR adjustment through R₂.





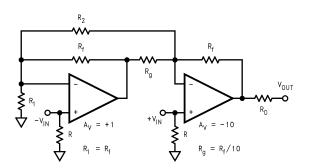


Figure 34. Differential Line Receiver with CMRR Adjustment

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NON-INVERTING CURRENT-FEEDBACK INTEGRATOR

The circuit of Figure 35 achieves its high speed integration by placing one of the LMH6715's amplifiers in the feedback loop of the second amplifier configured as shown.

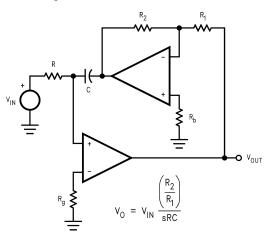


Figure 35. Current Feedback Integrator

LOW NOISE WIDE-BANDWIDTH TRANSIMPEDANCE AMPLIFIER

Figure 36 implements a low noise transimpedance amplifier using both channels of the LMH6715. This circuit takes advantage of the lower input bias current noise of the non-inverting input and achieves negative feedback through the second LMH6715 channel. The output voltage is set by the value of R_F while frequency compensation is achieved through the adjustment of R_T .

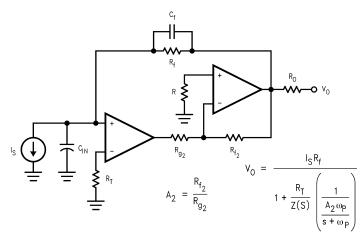


Figure 36. Low-Noise, Wide Bandwidth, Transimpedance Amp.

Revision History

Date Released	Revision	Section	Changes
11/30/2010	A	New Corporate Format Release	1 MDS data sheets converted into a Corp. data sheet format. Following MDS data sheet will be Archived MNLMH6715-X-RH, Rev. 0A0
07/12/2011	В	Connection Diagrams	Replaced 8 Lead CDIP (NAB0008A) diagram depicting single Op Amp with diagram depicting dual Op Amp.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-0254701QPA	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 125	LMH6715J-QML 5962-02547 01QPA Q ACO 01QPA Q >T	Samples
5962F0254701VPA	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 125	LMH6715JFQV 5962F02547 01VPA Q ACO 01VPA Q >T	Samples
LMH6715J-QML	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 125	LMH6715J-QML 5962-02547 01QPA Q ACO 01QPA Q >T	Samples
LMH6715JFQMLV	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 125	LMH6715JFQV 5962F02547 01VPA Q ACO 01VPA Q >T	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

2-May-2013

⁽⁴⁾ Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF LMH6715QML, LMH6715QML-SP :

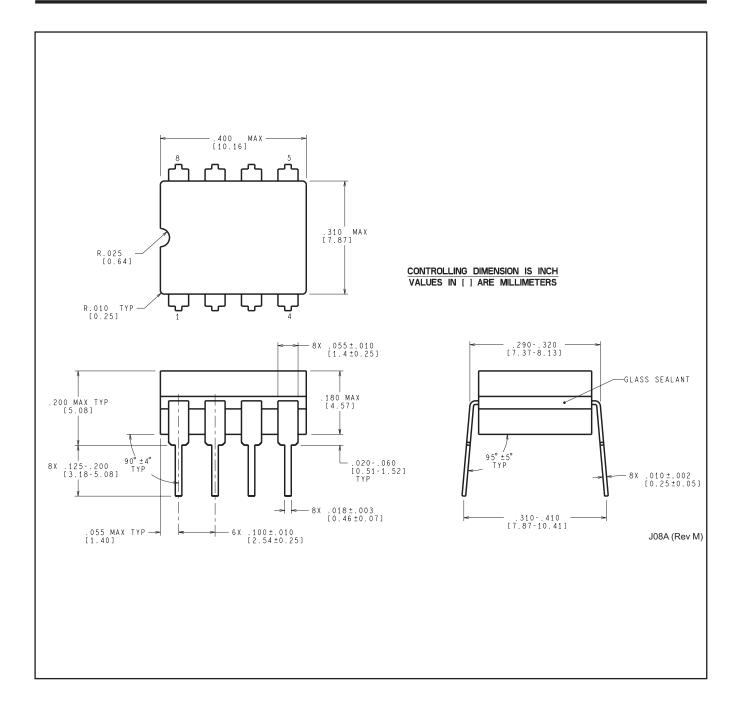
- Military: LMH6715QML
- Space: LMH6715QML-SP

NOTE: Qualified Version Definitions:

- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

MECHANICAL DATA

NAB0008A





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